

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2001-058352  
 (43)Date of publication of application : 06.03.2001

(51)Int.Cl. B29C 59/02  
 H01J 9/02  
 H01J 11/02

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## (30)Priority

Priority number : 11166434 Priority date : 14.06.1999 Priority country : JP

## (54) CONTACT TRANSFER METHOD AND APPARATUS AND TRANSFER MOLD

## (57)Abstract:

**PROBLEM TO BE SOLVED:** To obtain a transfer mold excellent in contact by imparting flexibility capable of following the unevenness of a substrate to a sheetlike mold having a recessed part fitted to a shape having to form a partition wall material.

**SOLUTION:** A transfer mold for forming the partition wall of a plasma display panel is used in transferring a transfer material to substrate to form the same on the substrate by filling the partition wall forming recessed part 104 of the transfer mold with the transfer material and bringing the transfer mold into close contact with the substrate being a transfer object on the transfer material filled side thereof. At this time, a reinforcing material 101 is laminated to the mold main body 103 of the transfer mold as a reinforcing layer to disperse the external force applied to the transfer mold to make the mold main body 103 hard to generate plastic deformation and a proper cushion layer 102 is provided between the reinforcing material 101 and the mold main body 103.

The main material of the transfer mold comprises a metal material with a thickness of 200  $\mu$ m-3 mm. By this constitution, a good result is obtained not only in the flowability to the substrate at a time of contact transfer but also the deformation of the transfer mold by bending or the like.

